

## . reescale Semiconductor Technical Data

# Low Distortion Wideband Amplifiers

Designed specifically for broadband applications requiring low distortion characteristics. Specified for use as return amplifiers for mid-split and high-split 2-way cable TV systems. Features all gold metallization system.

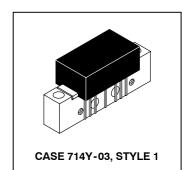
- Guaranteed Broadband Power Gain @ f = 5.0 200 MHz
- Guaranteed Broadband Noise Figure @ f = 5.0 175 MHz
- Superior Gain, Return Loss and DC Current Stability with Temperature
- All Gold Metallization
- All Ion-Implanted Arsenic Emitter Transistor Chips with 6.0 GHz f<sub>T</sub>'s
- Circuit Design Optimized for Good RF Stability Under High VSWR Load Conditions
- Transformers Designed to Insure Good Low Frequency Gain Stability versus Temperature

Document Number: MHW1224

Rev. 10, 1/2001

# MHW1224

22.0 dB 24.0 dB 5.0 - 200 MHz CATV HIGH-SPLIT REVERSE AMPLIFIERS



### **Table 1. Absolute Maximum Ratings**

| Rating                           | Symbol           | Value        | Unit |
|----------------------------------|------------------|--------------|------|
| RF Voltage Input (Single Tone)   | V <sub>in</sub>  | +65          | dBmV |
| DC Supply Voltage                | V <sub>CC</sub>  | +28          | Vdc  |
| Operating Case Temperature Range | T <sub>C</sub>   | - 20 to +100 | °C   |
| Storage Temperature Range        | T <sub>stg</sub> | - 40 to +100 | °C   |

**Table 2. Electrical Characteristics** ( $V_{CC} = 24 \text{ Vdc}$ ,  $T_{C} = +30^{\circ}\text{C}$ , 75  $\Omega$  system)

| Characteristic   | Symbol   | MHW1224                          | MHW1244                          | Units          |
|--|--|----------------------------------|----------------------------------|----------------|
| Power Gain @ 10 MHz  | G <sub>P</sub>   | $22.0 \pm 0.5$                   | 24.0 ± 0.5                       | dB             |
| Frequency Range (Response/Return Loss) Note 1  | BW   | 5.0-200                          |                                  | MHz            |
| Cable Slope Equivalent (5.0 - 200 MHz)   | S  | - 0.2 Min/+ 0.8 Max              |                                  | dB             |
| Gain Flatness (5.0 - 200 MHz)  | F  | ±0.2 Max                         |                                  | dB             |
| Input/Output Return Loss (5.0 - 200 MHz) Note 1  | IRL/ORL  | 18.0 Min                         |                                  | dB             |
| Cross Modulation Distortion @ +50 dBmV per ch. 12-Channel FLAT (5.0 - 120 MHz) 22-Channel FLAT (5.0 - 175 MHz) (2) (3) 26-Channel FLAT (5.0 - 200 MHz) | XM <sub>12</sub><br>XM <sub>22</sub><br>XM <sub>26</sub> | - 67 Typ<br>- 62 Max<br>- 62 Typ | - 66 Typ<br>- 61 Max<br>- 61 Typ | dB<br>dB<br>dB |

#### Notes:

- $1. \ \ Response \ and \ return \ loss \ characteristics \ are \ tested \ and \ guaranteed \ for \ the \ full \ 5.0 200 \ MHz \ frequency \ range.$
- 2. Freescale 100% distortion and noise figure testing is performed over the 5.0 175 MHz frequency range. Cross modulation and composite triple beat testing are with 22-channel loading; Video carriers used are:

3. Video carriers used for 12-Channel typical performances are T7 - 6; For 26-Channel typical performance, Channels 8, 9, 10 and 11 are added to the 22-Channel carriers listed above.





Table 2. Electrical Characteristics ( $V_{CC}$  = 24 Vdc,  $T_{C}$  = +30°C, 75  $\Omega$  system) (continued)

| Characteristic   | Symbol                                 | MHW1224                | MHW1244                | Units    |
|--|--|------------------------|------------------------|----------|
| Composite Triple Beat Distortion @ +50 dBmV per ch. 22-Channel FLAT (5.0 - 175 MHz) 26-Channel FLAT (5.0 - 200 MHz) Notes 2 and 3                                    | CTB <sub>22</sub><br>CTB <sub>26</sub> | - 69 Max<br>- 68.5 Typ | - 68 Max<br>- 67.5 Typ | dB<br>dB |
| Individual Triple Beat Distortion @ +50 dBmV per ch. Mid-Split (5.0 - 120 MHz) T11, T12 and CH2 @ 123.25 MHz High-Split (5.0 - 175 MHz) T13, CH2 and CH5 @ 175.5 MHz | ТВ <sub>3</sub><br>ТВ <sub>3</sub>     | - 88 Typ<br>- 85 Typ   | - 87 Typ<br>- 84 Typ   | dB<br>dB |
| Second Order Distortion @ +50 dBmV per ch.<br>High-Split (5.0 - 175 MHz) CH2, CHA @ 176.5 MHz  | IMD                                    | - 72 Max               | - 72 Max               | dB       |
| Noise Figure<br>High-Split (5.0 - 175 MHz) Note 2  | NF                                     | 5.5 Max                | 5.0 Max                | dB       |
| DC Current   | I <sub>DC</sub>                        | 210 Typ/240 Max        |                        | mAdc     |

#### Notes:

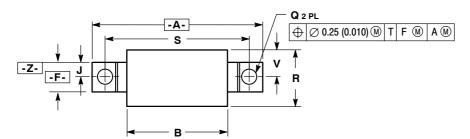
- 1. Response and return loss characteristics are tested and guaranteed for the full 5.0 200 MHz frequency range.
- 2. Freescale 100% distortion and noise figure testing is performed over the 5.0 175 MHz frequency range. Cross modulation and composite triple beat testing are with 22-channel loading; Video carriers used are:

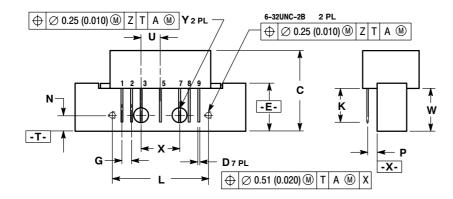
3. Video carriers used for 12-Channel typical performances are T7 - 6; For 26-Channel typical performance, Channels 8, 9, 10 and 11 are added to the 22-Channel carriers listed above.



**ARCHIVE INFORMATION** 

## **PACKAGE DIMENSIONS**





**CASE 714Y-03 ISSUE D** 

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

|     | INC       | HES   | MILLIMETERS |       |  |
|-----|-----------|-------|-------------|-------|--|
| DIM | MIN       | MAX   | MIN         | MAX   |  |
| Α   |           | 1.775 |             | 45.08 |  |
| В   |           | 1.085 |             | 27.56 |  |
| С   |           | 0.840 |             | 21.34 |  |
| D   | 0.018     | 0.022 | 0.46        | 0.56  |  |
| E   | 0.465     | 0.510 | 11.81       | 12.95 |  |
| F   | 0.300     | 0.325 | 7.62        | 8.25  |  |
| G   | 0.100 BSC |       | 2.54 BSC    |       |  |
| J   | 0.156 BSC |       | 3.96 BSC    |       |  |
| K   | 0.315     | 0.355 | 8.00        | 8.50  |  |
| L   | 1.00 BSC  |       | 25.40 BSC   |       |  |
| N   | 0.165 BSC |       | 4.19 BSC    |       |  |
| P   | 0.100 BSC |       | 2.54 BSC    |       |  |
| Q   | 0.148     | 0.168 | 3.76        | 4.27  |  |
| R   |           | 0.600 |             | 15.24 |  |
| S   | 1.500 BSC |       | 38.10 BSC   |       |  |
| U   | 0.200 BSC |       | 5.08 BSC    |       |  |
| ٧   |           | 0.250 |             | 6.35  |  |
| W   | 0.435     | 0.450 | 11.05       | 11.43 |  |
| Х   | 0.400     | BSC   | 10.16 BSC   |       |  |
| Υ   | 0.152     | 0.163 | 3.85        | 4.15  |  |

- STYLE 1:
  PIN 1: RF INPUT
  2: GROUND
  3: GROUND
  4: DELETED
  5: VDC
  6: DELETED
  7: GROUND
  8: GROUND
  9: RF OUTPUT

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